



2812

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Fritz Redeker et al.

Art Unit : Unknown

Serial No. : 09/918,591

Examiner : Unknown

Filed : July 27, 2001

Title : CHEMICAL MECHANICAL POLISHING OF A METAL LAYER WITH  
POLISHING RATE MONITORING

Commissioner for Patents  
Washington, D.C. 20231

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RESPONSE

In response to the action mailed March 14, 2002, please amend the application as follows:

In the claims:

1. (Amended) A method of chemical mechanical polishing a metal layer on a substrate, comprising:
- polishing the metal layer on the substrate at a first polishing station with a first polishing surface at a first polishing rate;
- monitoring polishing at the first polishing station with an eddy current monitoring system;
- transferring the substrate to a second polishing station when the eddy current monitoring system indicates that a predetermined thickness of the metal layer remains on the substrate;
- polishing the metal layer on the substrate at the second polishing station with a second polishing surface at a second polishing rate that is lower than the first polishing rate;
- monitoring polishing of the metal layer at the second polishing station with an optical monitoring system; and
- halting polishing when the optical monitoring system indicates that a first underlying layer is at least partially exposed.

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

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